

EP1145HSTSL-1.505M
[Click part number to visit Part Number Details page](#)
REGULATORY COMPLIANCE (Data Sheet downloaded on Jan 17, 2017)
[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.

**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 8 Pin DIP Metal Thru-Hole 1.505MHz ± 50 ppm -20°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	1.505MHz
Frequency Tolerance/Stability	± 50 ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Aging at 25°C	± 5 ppm/year Maximum
Operating Temperature Range	-20°C to +70°C
Supply Voltage	5.0Vdc $\pm 10\%$
Input Current	45mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	2.4Vdc Minimum (IOH=-16mA)
Output Voltage Logic Low (Vol)	0.4Vdc Maximum (IOL=+16mA)
Rise/Fall Time	4nSec Maximum (Measured at 0.8Vdc to 2.0Vdc)
Duty Cycle	50 $\pm 10\%$ (Measured at 1.4Vdc with TTL Load; Measured at 50% of waveform with HCMOS Load)
Load Drive Capability	10TTL Load Maximum
Output Logic Type	TTL
Pin 1 Connection	Tri-State (Disabled Output: High Impedance)
Pin 1 Input Voltage (Vih and Vil)	+2.0Vdc Minimum to enable output, +0.8Vdc Maximum to disable output, No Connect to enable output.
Disable Current	30mA Maximum (Pin 1 = Ground)
Standby Current	50 μ A Maximum (Pin 1 = Ground)
Peak to Peak Jitter (tPK)	500pSec Maximum, 90pSec Typical
RMS Period Jitter (tRMS)	50pSec Maximum, 13pSec Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

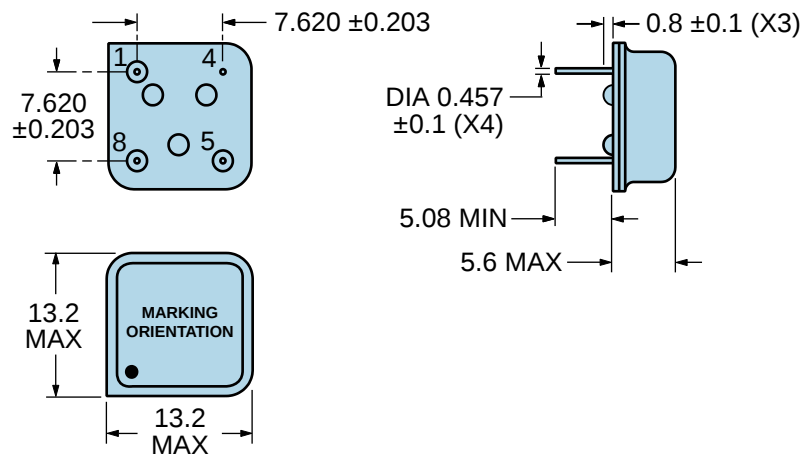
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State (High Impedance)
4	Case/Ground
5	Output
8	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	EP11TS EP11=Product Series
3	1.5050M
4	XXYZZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

OUTPUT WAVEFORM & TIMING DIAGRAM



EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

Test Circuit for CMOS Output



Note 1: An external $0.1\mu\text{F}$ low frequency tantalum bypass capacitor in parallel with a $0.01\mu\text{F}$ high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance ($<12\text{pF}$), 10X attenuation factor, high impedance ($>10\text{Mohms}$), and high bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)		3°C/Second Maximum
Preheat		
- Temperature Minimum (TS MIN)		150°C
- Temperature Typical (TS TYP)		175°C
- Temperature Maximum (TS MAX)		200°C
- Time (ts MIN)		60 - 180 Seconds
Ramp-up Rate (TL to TP)		3°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)		217°C
- Time (tL)		60 - 150 Seconds
Peak Temperature (TP)		260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (TP Target)		250°C +0/-5°C
Time within 5°C of actual peak (tP)		20 - 40 Seconds
Ramp-down Rate		6°C/Second Maximum
Time 25°C to Peak Temperature (t)		8 Minutes Maximum
Moisture Sensitivity Level		Level 1

EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 185°C

TS MAX to TL (Ramp-up Rate)		5°C/Second Maximum
Preheat		
- Temperature Minimum (TS MIN)	N/A	
- Temperature Typical (TS TYP)	150°C	
- Temperature Maximum (TS MAX)	N/A	
- Time (ts MIN)	60 - 120 Seconds	
Ramp-up Rate (TL to TP)		5°C/Second Maximum
Time Maintained Above:		
- Temperature (TL)	150°C	
- Time (tL)	200 Seconds Maximum	
Peak Temperature (TP)		185°C Maximum
Target Peak Temperature (TP Target)		185°C Maximum 2 Times
Time within 5°C of actual peak (tp)		10 Seconds Maximum 2 Times
Ramp-down Rate		5°C/Second Maximum
Time 25°C to Peak Temperature (t)		N/A
Moisture Sensitivity Level		Level 1

EP1145HSTSL-1.505M

[Click part number to visit Part Number Details page](#)

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	30 - 60 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	245°C Maximum
Target Peak Temperature (TP Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (tP)	5 Seconds Maximum 1 Time / 15 Seconds Maximum 2 Times
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.